# bq28z610EVM 1- to 2-Series Li-Ion Battery Pack Manager Evaluation Module

This evaluation module (EVM) is a complete evaluation system for the bq28z610 or bq294502 battery management system. The EVM includes one bq28z610 and bq294502 circuit module and a link to Windows® based PC software. The circuit module includes one bq28z610 integrated circuit (IC), one bq294502 IC, and all other onboard components necessary to monitor and predict capacity, perform cell balancing, monitor critical parameters, protect the cells from overcharge, over-discharge, short-circuit, and over-current in 1- or 2-series cell Li-Ion or Li-Polymer battery packs. The circuit module connects directly across the cells in a battery. With the EV2300 or EV2400 interface board and software, the user can read the bq28z610 data registers, program the chipset for different pack configurations, log cycling data for further evaluation, and evaluate the overall functionality of the solution under different charge and discharge conditions using HDQ communication protocol.

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# 1 Features

- Complete evaluation system for the bq28z610EVM 1- to 2-Series Battery Pack Manager Evaluation Module and bq294502 independent overvoltage protection IC
- Populated circuit module for quick setup
- Software that allows data logging for system analysis

## 1.1 Kit Contents

- bq28z610 and bq294502 circuit module
- Cable to connect the EVM to an EV2300 or EV2400 Communications Interface adapter

## 1.2 Ordering Information

For complete ordering information, see the product page at www.ti.com.

**Table 1. Ordering Information**

| EVM PART NUMBER | CHEMISTRY | CONFIGURATION | CAPACITY |
|---|---|---|---|
| bq28z610EVM | Li-Ion | 1-, 2-cell | Any |

## 1.3 Documentation

For information on the bq28z610 and bq294502 device firmware and hardware, see the following documentation:

- *bq28z610 Impedance Track™ Gas Gauge for 1-Series to 2-Series Li-Ion/Li-Polymer Battery Packs* (SLUSAS3)
- *bq28z610 Technical Reference Manual* (SLUUA65)
- *bq2945xx Overvoltage Protection For 2-Series and 3-Series Cell Li-Ion Batteries* (SLUSAJ3)
- *bq294502 EVM User's Guide* (SLUU659)

## 1.4 bq28z610 and bq294502 Circuit Module Performance Specification Summary

This section summarizes the performance specifications of the bq28z610 and bq294502 EVM.

**Table 2. Performance Specification Summary**

| SPECIFICATION | MINIMUM | TYPICAL | MAXIMUM | UNITS |
|---|---|---|---|---|
| Input voltage Pack+ to Pack– | 3 | 7 | 25 | V |
| Charge and discharge current | 0 | 2 | 7 | A |

# 2 bq28z610EVM Quick Start Guide

This section provides the step-by-step procedures required to use a new EVM and configure it for operation in a laboratory environment.

## 2.1 Items Needed for EVM Setup and Evaluation

- bq28z610 and bq294502 circuit module
- EV2300 or EV2400 communications interface adapter
- Cable to connect the EVM to an EV2300 or EV2400 communications interface adapter
- USB cable to connect the communications interface adapter to the computer
- Computer setup with Windows® XP, or higher, operating system
- Access to the Internet to download the Battery Management Studio software setup program
- One or two battery cells or 1-kΩ resistors to configure a cell simulator
- A DC power supply that can supply 8.4 V and 2 A (constant current and constant voltage capability is desirable)

## 2.2 Software Installation

Find the latest software version in the bq28z610 tool folder on www.ti.com. Use the following steps to install the bq28z610 Battery Management Studio software:

1. Download and run the Battery Management Studio setup program from the Development Tools section of the bq28z610EVM product folder on www.ti.com. See Section 3 for detailed information on using the tools in the Battery Management Studio.
2. If the Communications Interface Adapter was not previously installed, after the bqStudio installation, a TI USB DRIVER INSTALLER pops up. Click **Yes** for the agreement message and follow its instructions. Two drivers are associated with the EV2300 and an additional file may be required for the EV2400. Follow the instructions to install both. Do not reboot the computer, even if asked to do so.
3. Plug the communications interface adapter into a USB port using the USB cable. The Windows® system may show a prompt that new hardware has been found. When asked, "Can Windows connect to Windows Update to search for software?", select "No, not this time", and click **Next**. In the next dialog window, it indicates "This wizard helps you install software for: TI USB Firmware Updater". Select "Install the software automatically (Recommended)" and click **Next**. It is common for the next screen to be the Confirm File Replace screen. Click **No** to continue. If this screen does not appear, then go to the next step. After Windows® indicates that the installation was finished, a similar dialog window pops up to install the second driver. Proceed with the same installation preference as the first one. The second driver is TI USB bq80xx Driver.

## 2.3 EVM Connections Module Connections

This section covers the hardware connections for the EVM. See Figure 1.

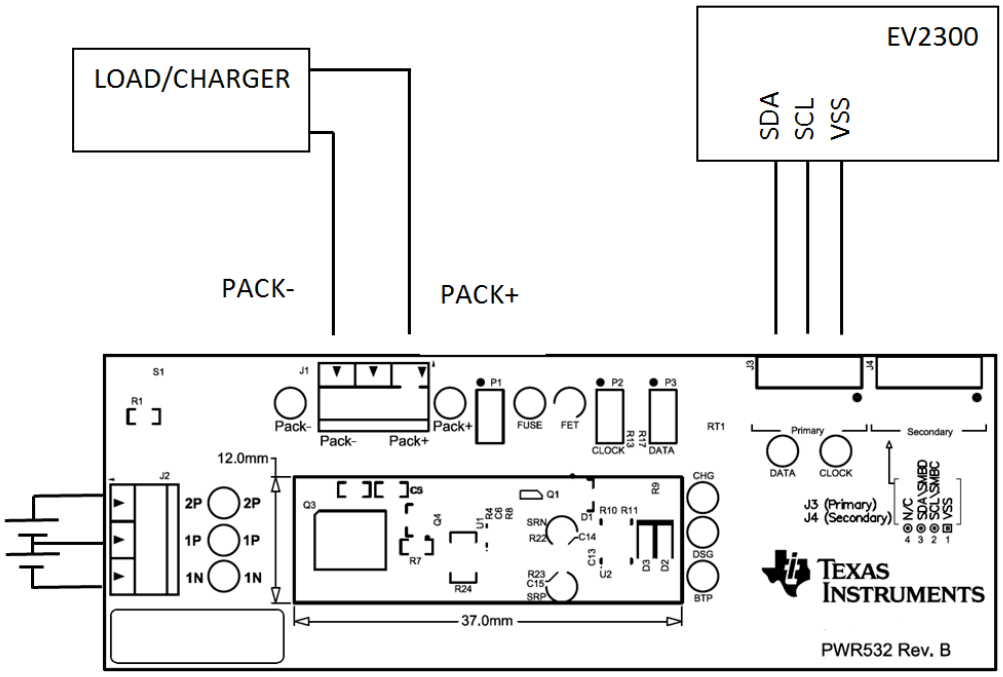


**Figure 1. bq28z610 Circuit Module Connection to Cells and System Load or Charger**

- Direct connection to the cells: 1N (BAT–), 1P, 2P (BAT+)

  Attach the cells to the J2 terminal block. A specific cell connection sequence is not required, although it is a good practice to start with lowest cell in the stack (cell1) and then add cell 2. The U1 and U2 devices should not get damaged by other cell connection sequences, but there is a possibility that the bq294502 could blow the fuse in a module that has one. Attaching cells starting with cell 1 should eliminate this risk.

| Number of Cells | J2 Terminal Block Connections | | | | |
|---|---|---|---|---|---|
| | 1N | | 1P | | 2P |
| 1 | ⊖ | –cell1+ | ⊖ | short | ⊖ |
| 2 | ⊖ | –cell1+ | ⊖ | –cell2+ | ⊖ |

**Figure 2. Cell Connection Configuration**

A resistor cell simulator can be used instead of battery cells. Connect a resistor between each of the contacts on the J2 connector; that is, from 1N to 1P and from 1P to 2P. If being used for a 1-series configuration no resistor is needed, simply short 1P and 2P. A power supply can provide power to the cell simulator. Set the power supply to the desired cell voltage x the number of cells and attach the ground wire to 1N and the positive wire to 2P. For example, for a 2-series configuration with a 3.6-V cell voltage, set the power supply to 2 × 3.6 = 7.2 V.

- $I^2C$™ (SDA, SCL)

  Attach the communications interface adapter cable to J3 and to the $I^2C$™ port on the EV2300.

**NOTE:** If the EV2300 is used, ensure that shunts are placed on P2 and P3 jumpers to enable the onboard pull-up resistors. The EV2400 has internal pull-up resistors if it is used.

- System load and charger connections across PACK+ and PACK–

  Attach the load or power supply to the J1 terminal block. The positive terminal of the load or power supply wire should be connected to the terminal block position labeled PACK+. The ground wire for the load or power supply should be connected to the other terminal block position labeled PACK–.

- Wake-up the device up from SHUTDOWN (WAKE)

  Press the **Wake** pushbutton switch S1 to temporarily connect BAT+ to PACK+. This applies voltage to the PACK pin on the bq28z610 to power-up the regulators and start the initialization sequence.

- Parameter setup

  The default data flash default settings is configured for 2-series Li-Ion cells. The user should change the | Data Memory | Settings | DA Configuration register to set up the number of series cells to match the physical pack configuration by clearing the CCO flag for 1-series configuration or setting it for 2-series configuration. This provides basic functionality to the setup. Other data flash parameters should also be updated to fine tune the gauge to the pack. See the *bq28z610 Technical Reference Manual* (SLUUA65) for help with setting the parameters.

# 3 Battery Management Studio

## 3.1 Starting the Program

Run Battery Management Studio from the Start | Programs | Texas Instruments | Battery Management Studio sequence or the Battery Management Studio shortcut. As long as the device has been woken up from shutdown mode by momentarily pressing button **S1** or applying a charger voltage, the gauge will be automatically detected and the register screen will appear as seen in Figure 3. If your device contains an earlier firmware version, then auto detection of the device may not occur. If that happens, on the window that pops up as shown in Figure 4, select any bq28z610 .bqz file. This action will enable the program to get started and the user can update the firmware using the latest .srec file for the device downloadable from the product folder of the gauge at www.ti.com.

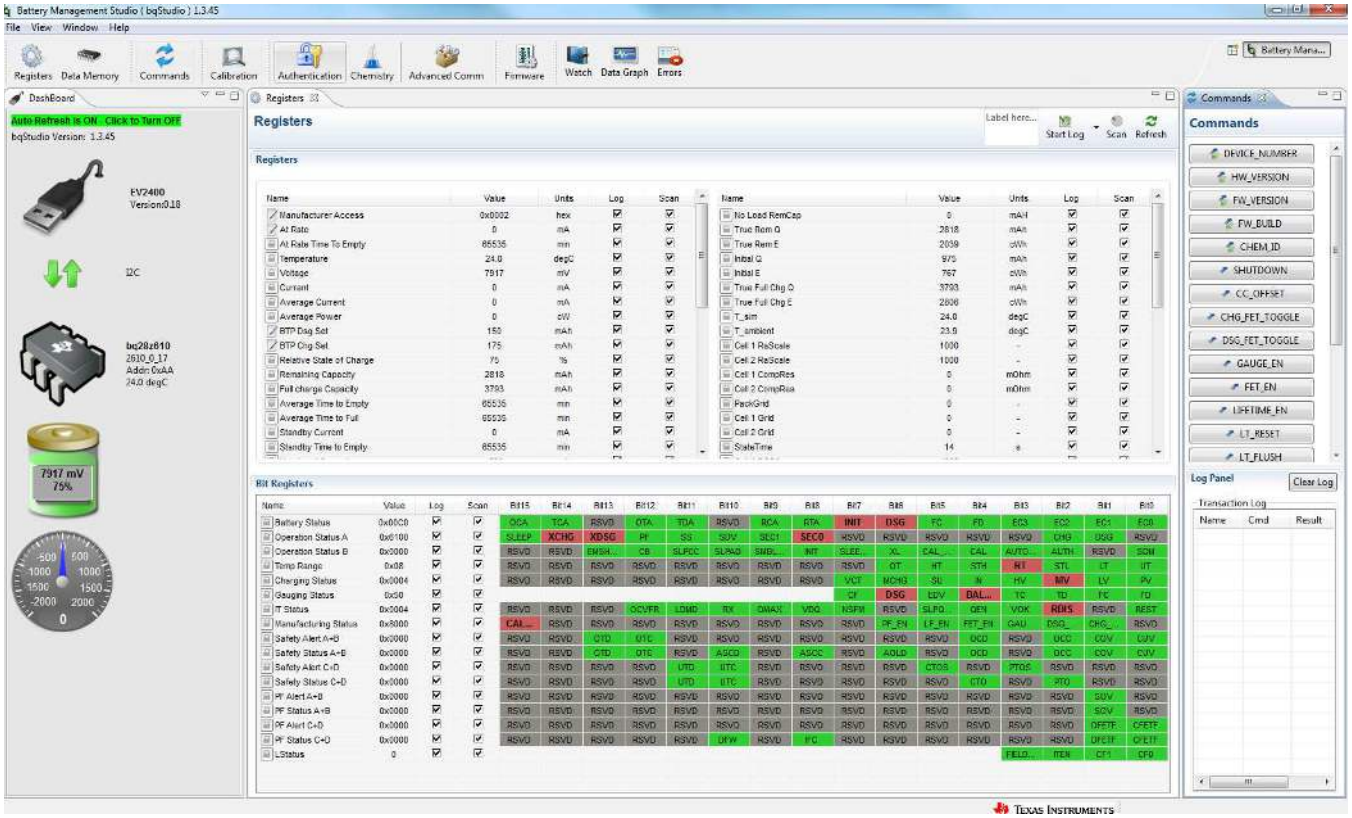


**Figure 3. Registers Screen**

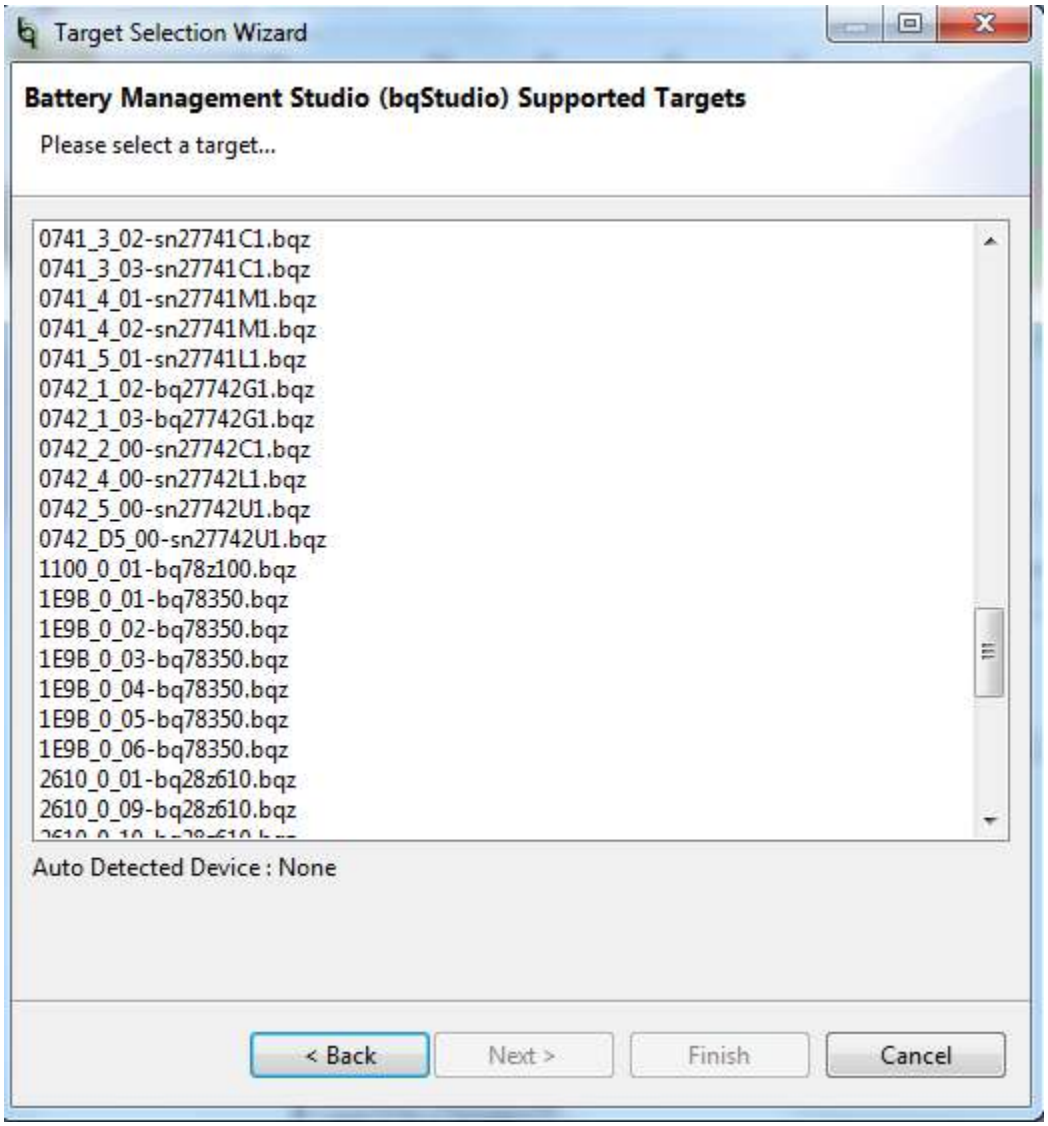


**Figure 4. Battery Management Studio Supported Targets**

## 3.2 Registers Screen

The Registers section contains parameters used to monitor gauging. The Bit Registers section provides bit level picture of status and fault registers. A green flag indicates that the bit is 0 (low state) and a red flag indicates that the bit is 1 (high state). A greyed out bit indicated that bit is reserved. Data begins to appear once the **Refresh** (single-time scan) button is selected, or it scans continuously if the **Scan** button is selected. The continuous scanning period can be set via the | Windows |preferences| register selections.

The battery management Studio program provides a logging function which logs all the values of the parameters in the Register section if running the program in “Show basic view mode”. In order to selectively choose the parameters of Register section that are scanned and logged, the user needs to set Battery Management Studio to “Show Advanced view mode”. This mode can be set via | Windows |preferences| All Global Settings| Show Advanced Views. Uncheck the fields that are not needed to be scanned or logged. To enable logging, select the **Log** button; this causes the **Scan** button to be selected. When logging is stopped, the **Scan** button is still selected and has to be manually deselected.

## 3.3 Data Memory Screen

The bq28z610 data flash comes configured per the default settings detailed in the bq28z610 TRM. Ensure that the settings are correctly changed to match the pack and application for the solution being evaluated. For ease of configuration, a text file with a gg.csv extension can be extracted, modified and imported back on the device. Use the export and import buttons as seen in Figure 5 to export and import gg.csv files. The auto export button enables gg files to be exported periodically at intervals. This is useful when debugging issues with the gauge. A write all command is necessary if a gg.csv file is imported to ensure that all the changes made on the gg.csv file are effected on the gauge. The read all command is used to read back all of the data written to the gauge so that the changes made can be verified. The filter/search field enables the user to search for a particular parameter in the data memory content.

**NOTE:** Do not make modifications to the gg.csv file using Microsoft Excel® as it makes changes to file, which bqStudio rejects. Make sure to use a text editor like notepad or similar to edit a gg.csv file.

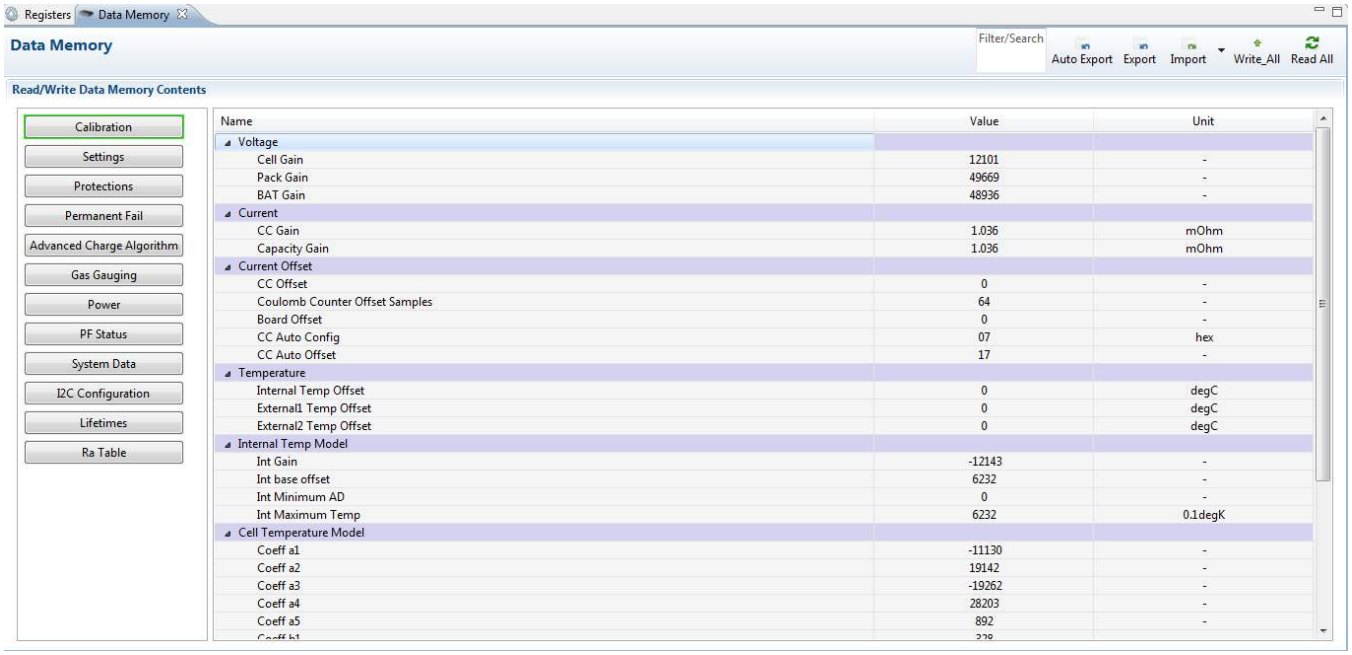


**Figure 5. Data Memory Screen**

## 3.4 Calibration Screen

The voltages, temperatures, and currents should be calibrated to provide good gauging performance. Press the **Calibration** button while in the “Show Advanced view mode” to select the **Advanced Calibration** window. See Figure 6. If in the “Show basic view mode”, the basic calibration window shows when the **Calibration** button is clicked. The **Advanced Calibration** window enables the internal temperature sensor as well as the external thermistor to be calibrated.

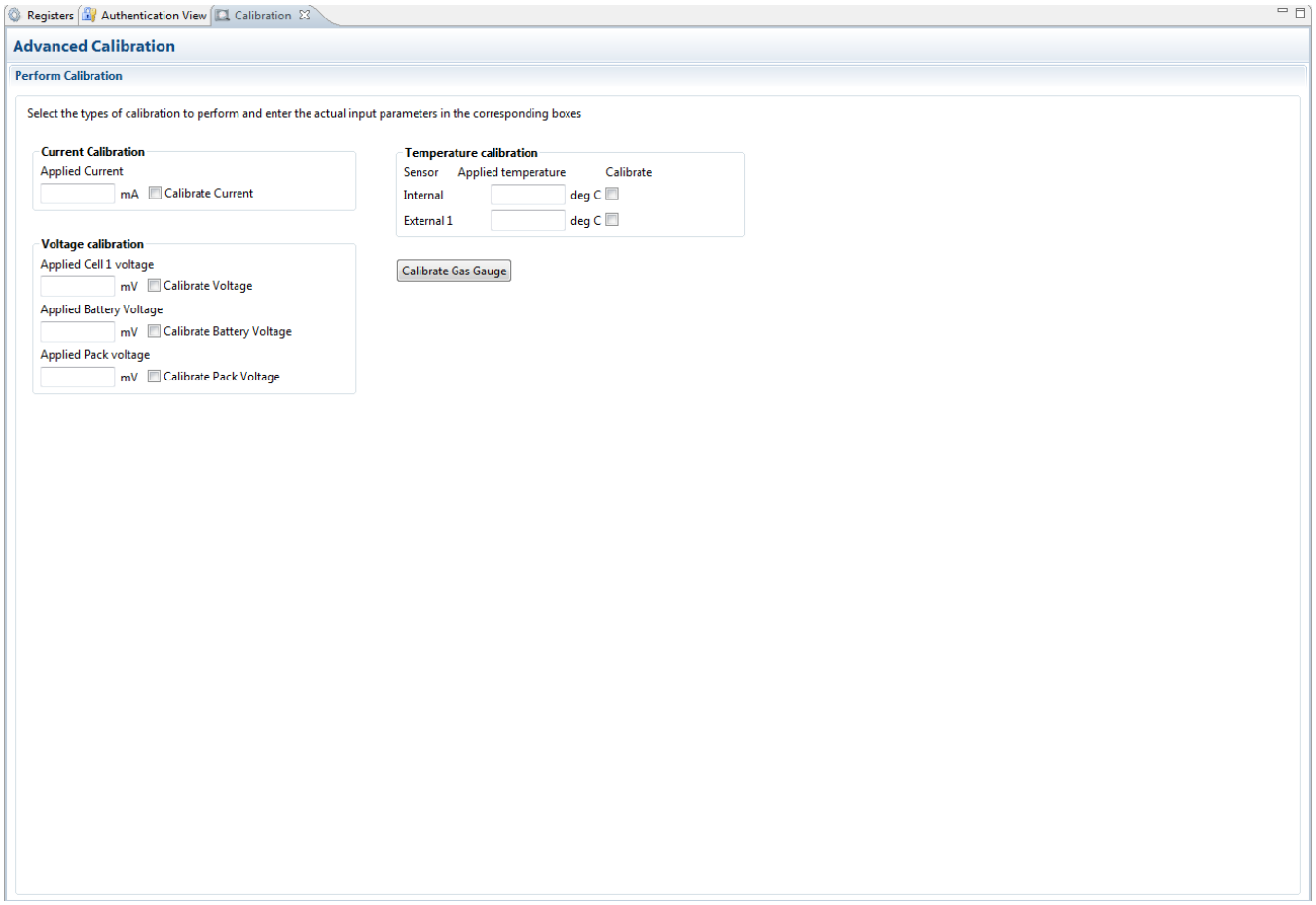


**Figure 6. Calibration Screen**

### 3.4.1 Voltage Calibration

- Measure the voltage from Cell 1 to 1N and enter this value in the *Applied Cell 1 Voltage* field and select the **Calibrate Voltage** box.
- Measure the voltage from Bat+ (2P) to Bat– (2N) and enter this value in the *Applied Battery Voltage* field and select the **Calibrate Battery Voltage** box.
- Measure the voltage from Pack+ to Pack– and enter this value in the *Applied Pack Voltage* field and select the **Calibrate Pack Voltage** box. If the voltage is not present, then turn the charge and discharge FETs on by entering a 0x22 command in the Manufacturer Access register on the **Register** screen.
- Press the **Calibrate Gas Gauge** button to calibrate the voltage measurement system.
- Deselect the **Calibrate Voltage** boxes after voltage calibration has completed.

### 3.4.2 Temperature Calibration

- Enter the room temperature in each of the *Applied Temperature* fields and select the **Calibrate** box for each thermistor to be calibrated. The temperature values must be entered in degrees Celsius.
- Press the **Calibrate Gas Gauge** button to calibrate the temperature measurement system.
- Deselect the **Calibrate** boxes after temperature calibration has completed.

### 3.4.3 Current Calibration

The Board Offset calibration option is not offered in Battery Management Studio, because it is not required when using the bq28z610EVM. The Board Offset calibration option is available in bqProduction.

- Connect and measure a 2-A current source from 1N (–) and Pack– to calibrate without using the FETs. (TI does not recommend calibration using the FETs.)
- Enter –2000 in the *Applied Current* field and select the **Calibrate Current** box.
- Press the **Calibrate Gas Gauge** button to calibrate.
- Deselect the **Calibrate Current** box after current calibration has completed.

## 3.5 Authentication Screen

The bq28z610 supports SHA-1 HMAC authentication with the host system. The authentication screen of bqStudio allows for the SHA-1 calculator to be tested, perform gauge authentication by the host and change the gauge authentication key.

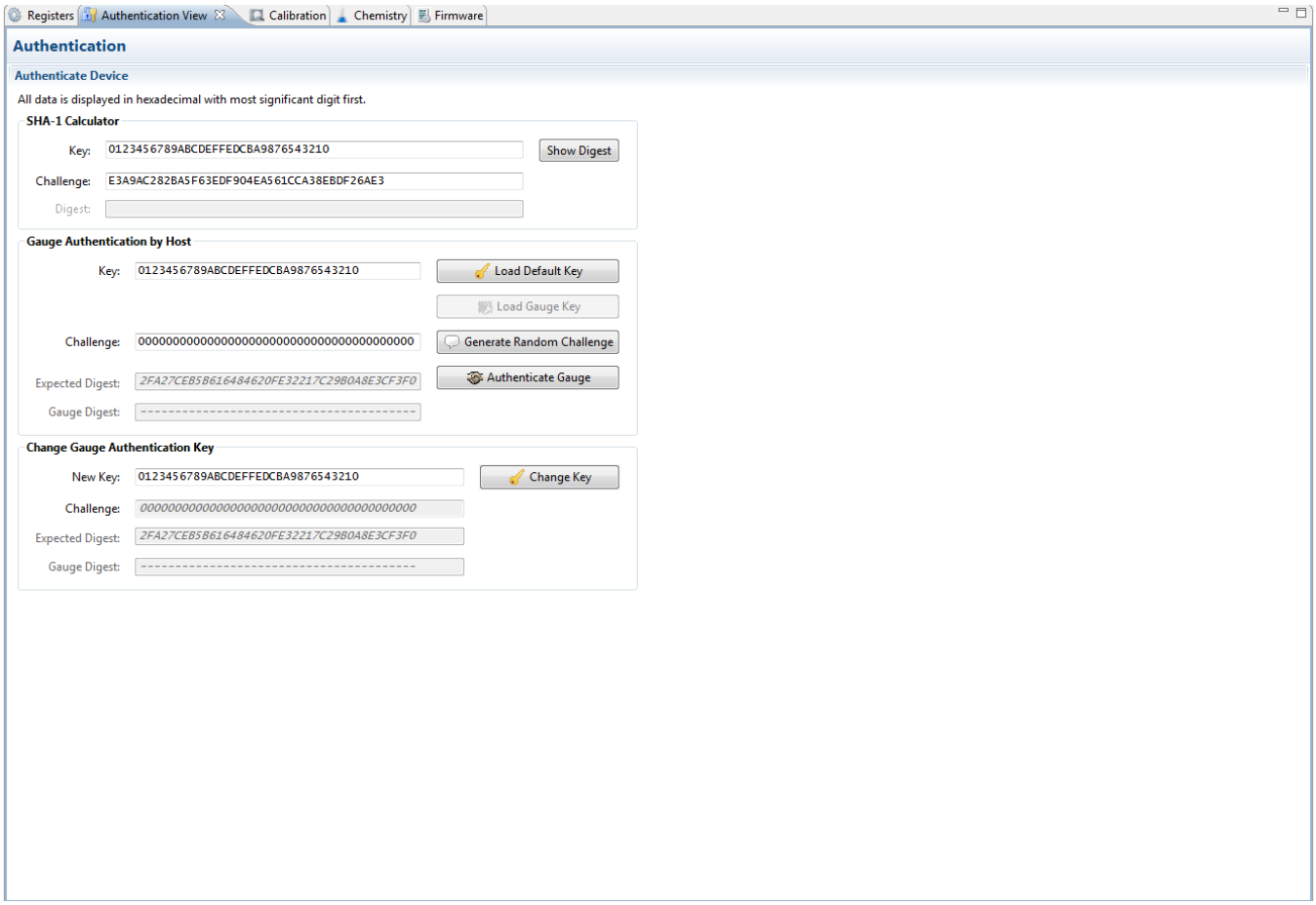


**Figure 7. Authentication Screen**

## 3.6 Chemistry Selection

The chemistry file contains parameters that the simulations use to model the cell and its operating profile. It is critical to program a Chemistry ID that matches the cell into the device. Some of these parameters can be viewed in the Data Flash section of the Battery Management Studio.

Press the **Chemistry** button to select the **Chemistry** window.

- The table can be sorted by clicking the desired column. For example: Click the *Chemistry ID* column header.
- Select the ChemID that matches your cell from the table (see Figure 8).
- Press **Update Chemistry from Database** to update the chemistry in the device.

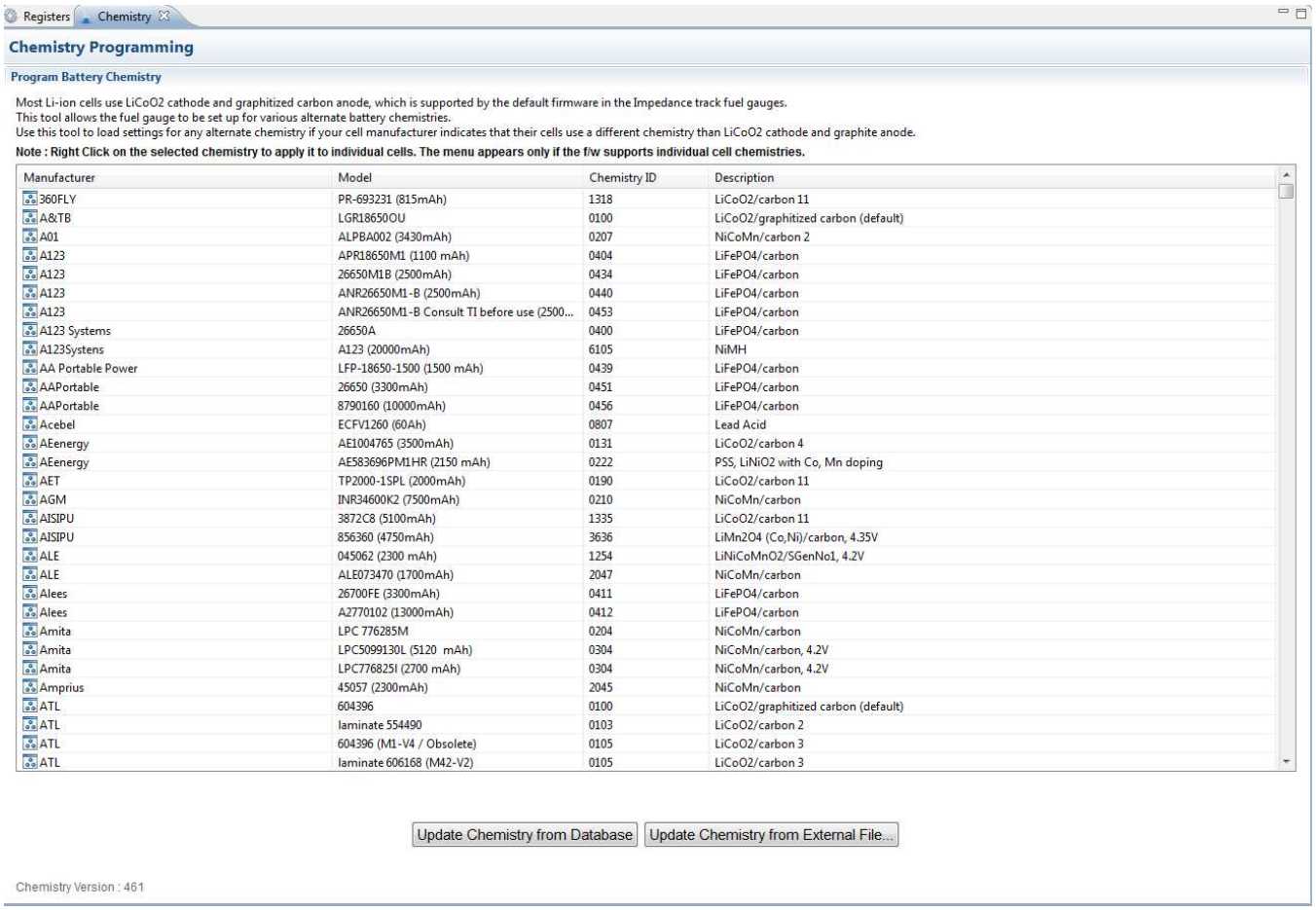


**Figure 8. Chemistry Screen**

## 3.7 Firmware Screen

Press the **Firmware** button to select the **Firmware Update** window. This window allows the user to export and import the device firmware.

### 3.7.1 Programming the Flash Memory

The upper section of the Firmware screen is used to initialize the device by loading the default .srec into the flash memory (see Figure 9).

- Search for the .srec file using the **Browse** button.
- Select the **Execute after programming** box to automatically return the device to NORMAL mode after programming has completed.
- Press the **Program** button and wait for the download to complete.

### 3.7.2 Exporting the Flash Memory

The lower section of the Firmware screen is used to export all of the flash memory from the device (see Figure 9).

- Press the **Browse** button and enter an .srec filename.
- Press the *Read Srec* to save the flash memory contents to the file. Wait for the download to complete.

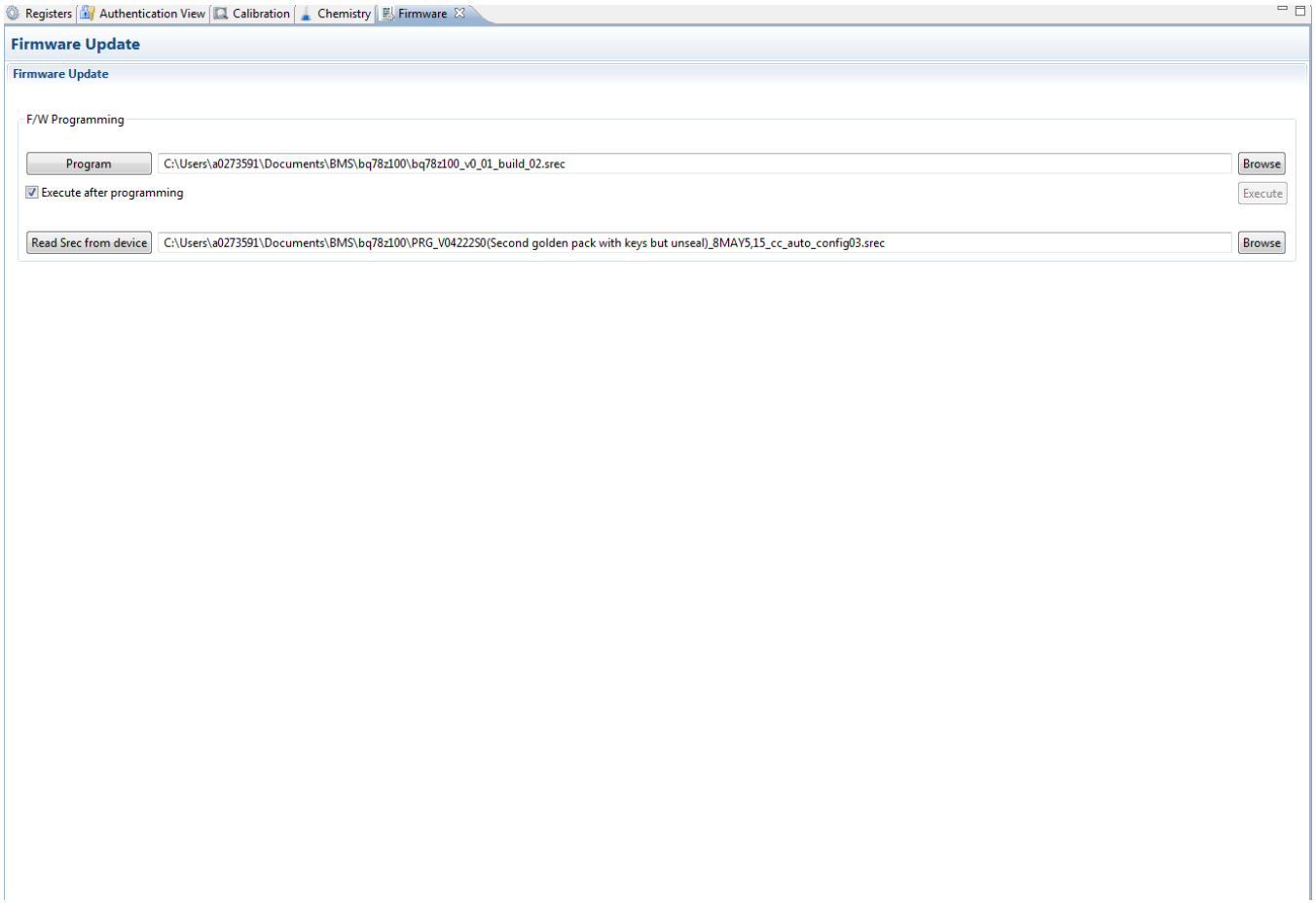


**Figure 9. Firmware Screen**

## 3.8 Advanced Comm I²C Screen

Press the **Advanced Comm I2C** button to select the **Advanced Comm I2C** window. This tool provides access to parameters using I²C and Manufacturing Access commands. See Figure 10. The transaction log screen shows the history of sent commands.

**NOTE:** I²C commands are sent in Little Endian format.

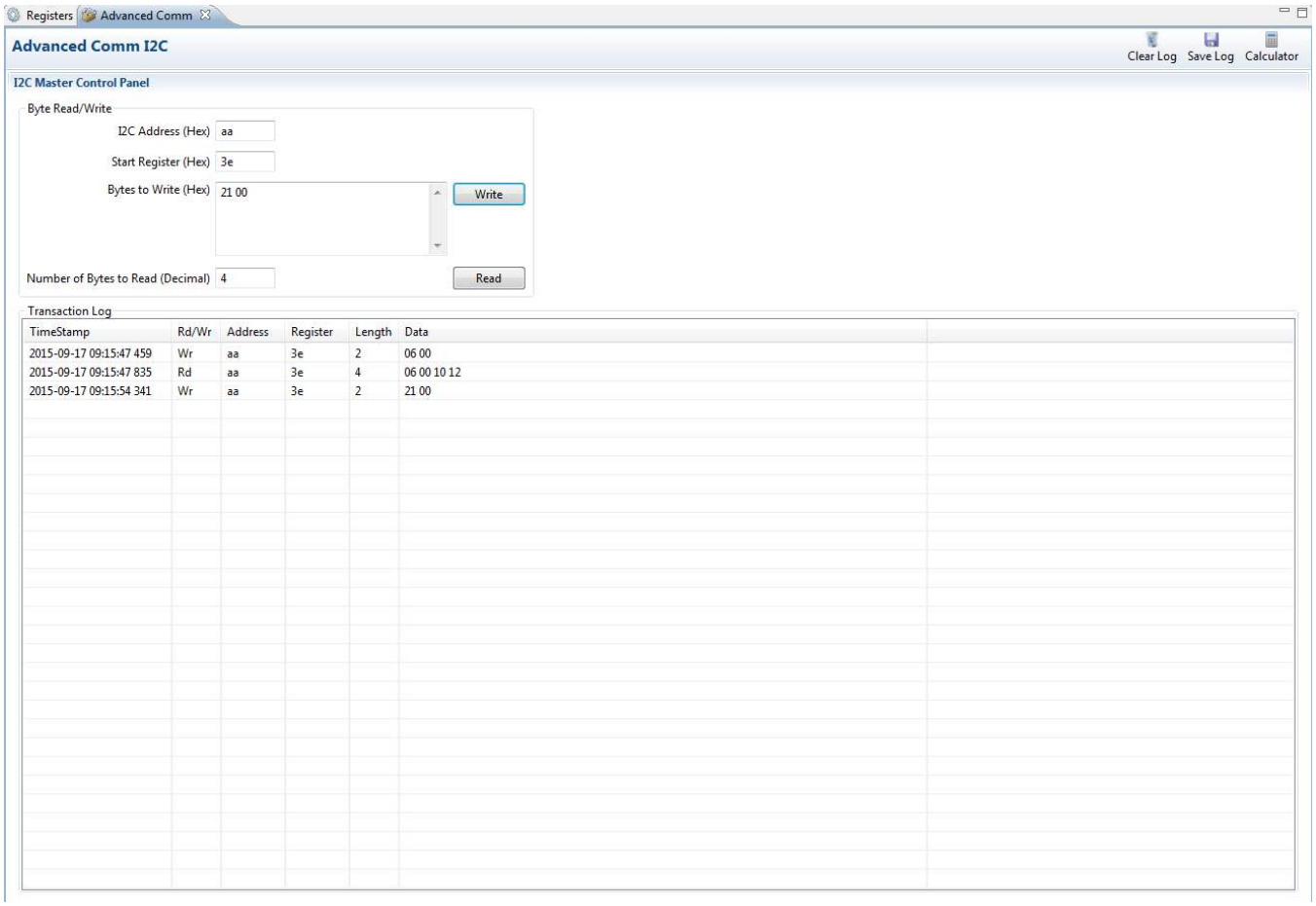


**Figure 10. Advanced Comm I²C Screen**

**Examples:**

Reading an I²C Command.

- Read chemical ID (0x 0006).
  - Write to mac address 3e Command 06 00 (see Figure 10).
  - Read 4 bytes.
  - The result returned is 10 12, which is little endian for chem id 1210.

Sending a MAC *Gauging()* to enable IT via *ManufacturerAccess()*.

- With Impedance Track™ disabled, send *Gauging()* (0x0021) to *ManufacturerAccess()*.
  - Write to mac address 3e command 21 00 (see Figure 10).

## 3.9 Watch Screen

This enables monitoring of specific registers and data memory items at user specified time intervals. By clicking the add register or add data memory item, these will be added to the table of values to be tracked.

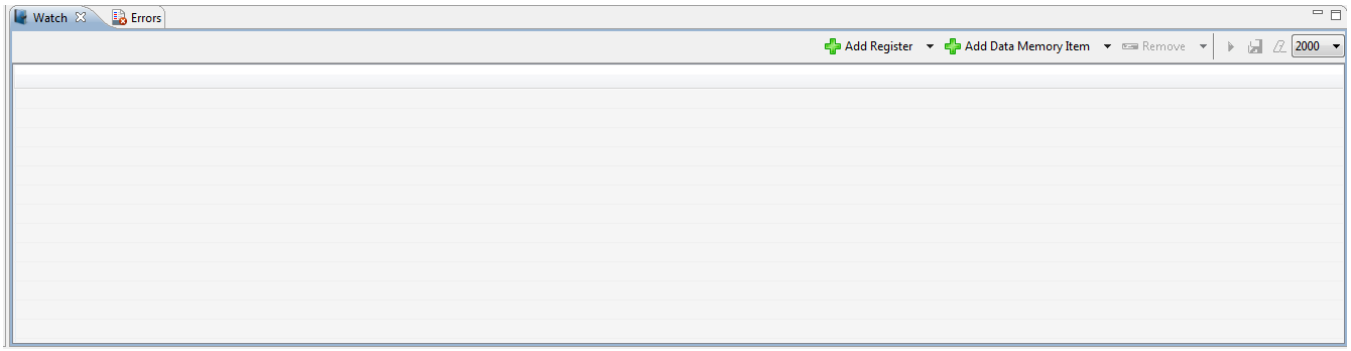


**Figure 11. Watch Screen**

## 3.10 Data Graph Screen

This enables specified registers and data memory items to be plotted in a graph real time based on a specific time interval chosen as shown in Figure 12.

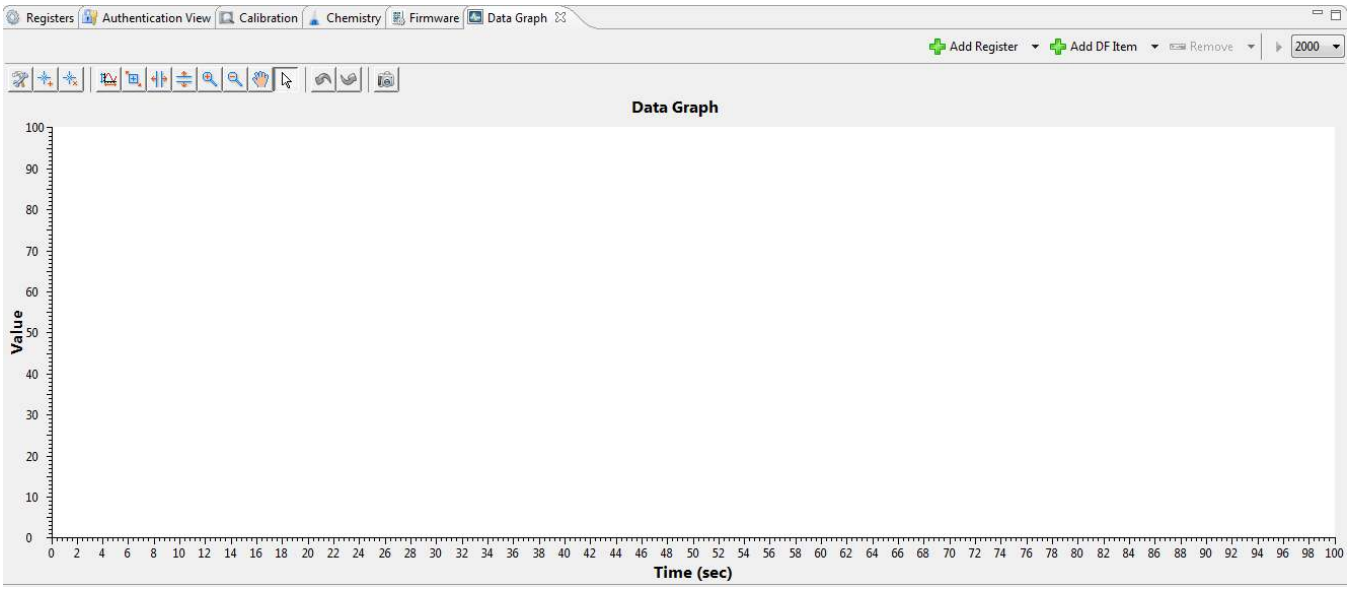


**Figure 12. Data Graph Screen**

## 3.11 Error Screen

This keeps track of any error that may occur with bqStudio during usage.

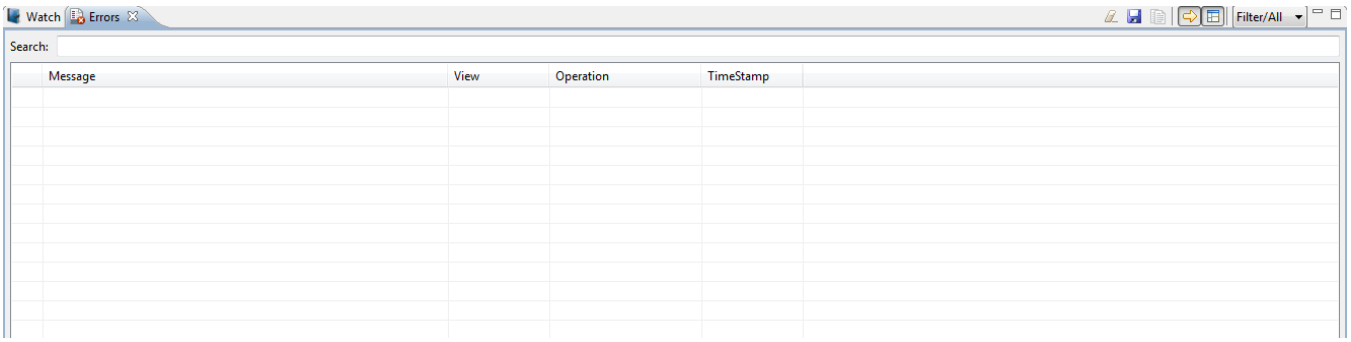


**Figure 13. Error Screen**

# 4 Circuit Module Physical Layouts and Bill of Materials

This section contains the printed-circuit board (PCB) layout, bill of materials, and assembly drawings for the bq28z610/bq294502 circuit modules.

## 4.1 Board Layout

This section shows the dimensions, PCB layers (see Figure 14 through Figure 19), and assembly drawing for the bq28z610 modules.

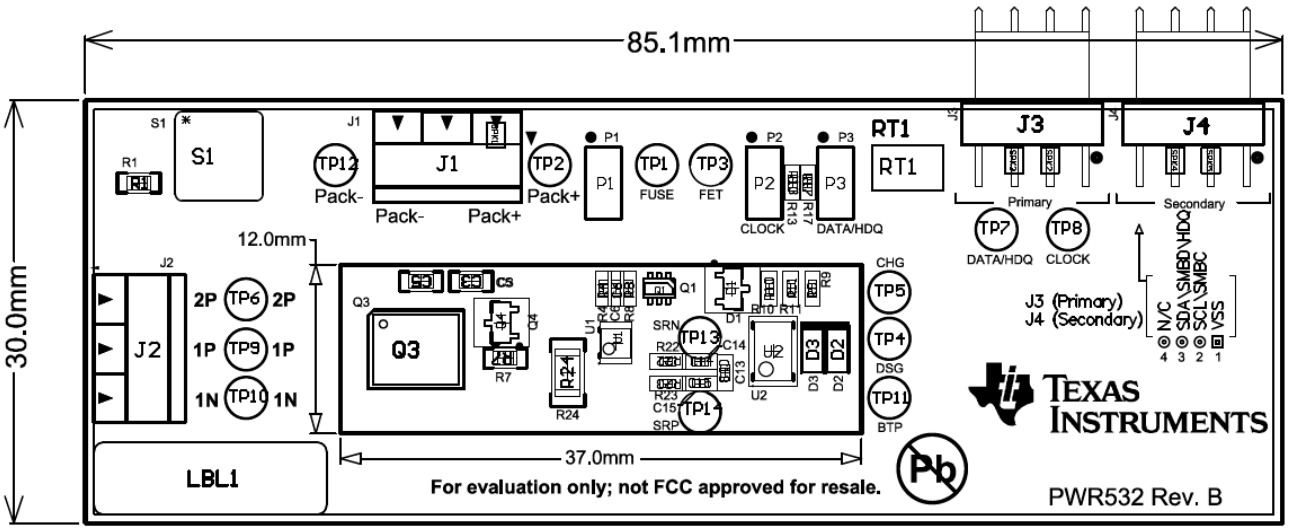


**Figure 14. Top Silk Screen**

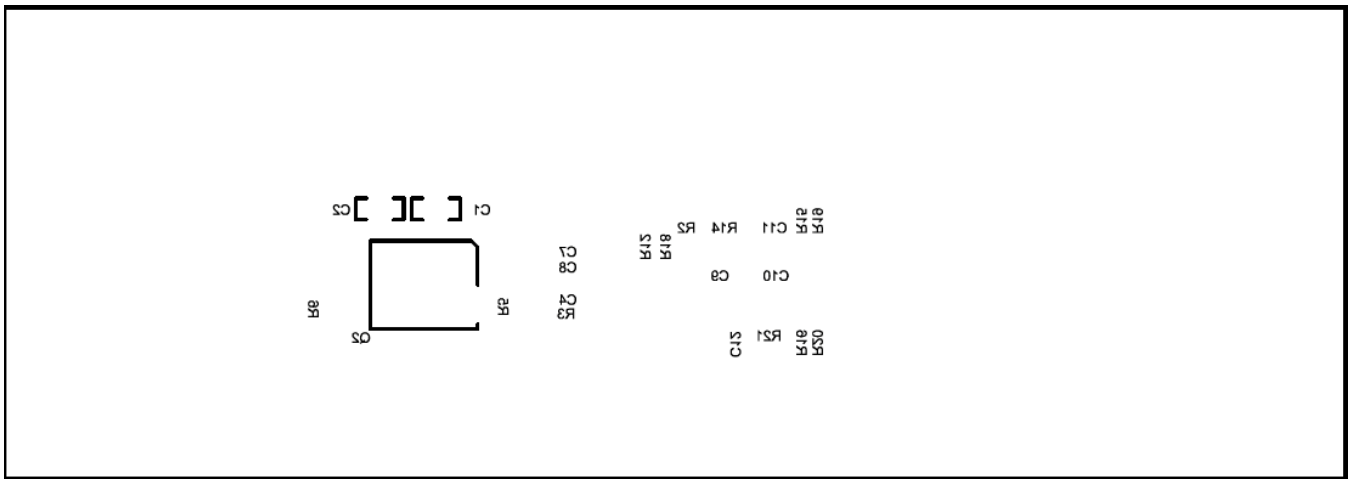

**Figure 15. Bottom Silk Screen**

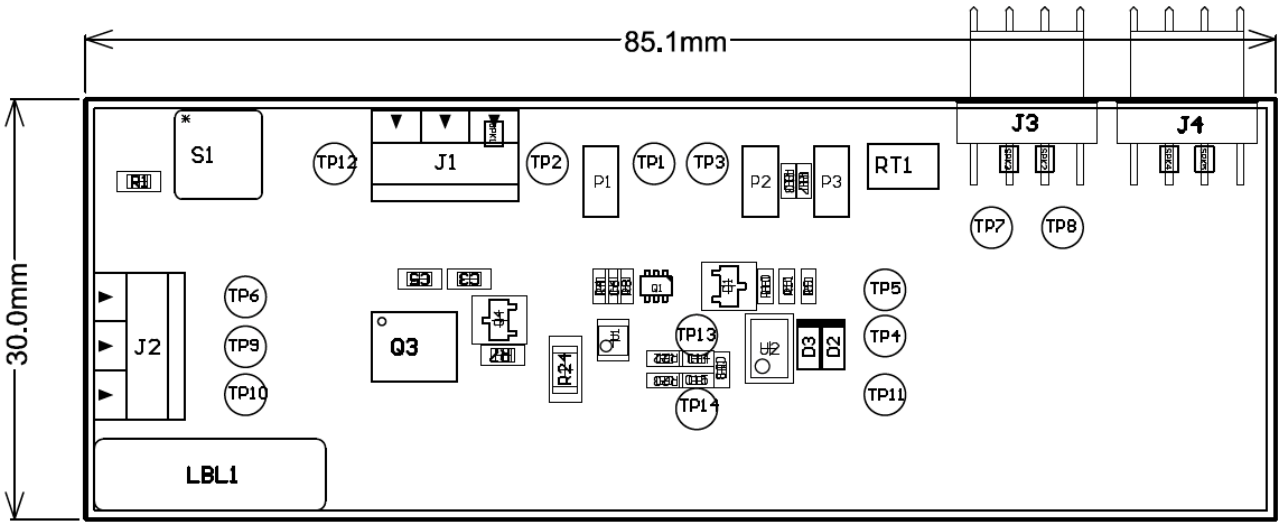


**Figure 16. Top Assembly**

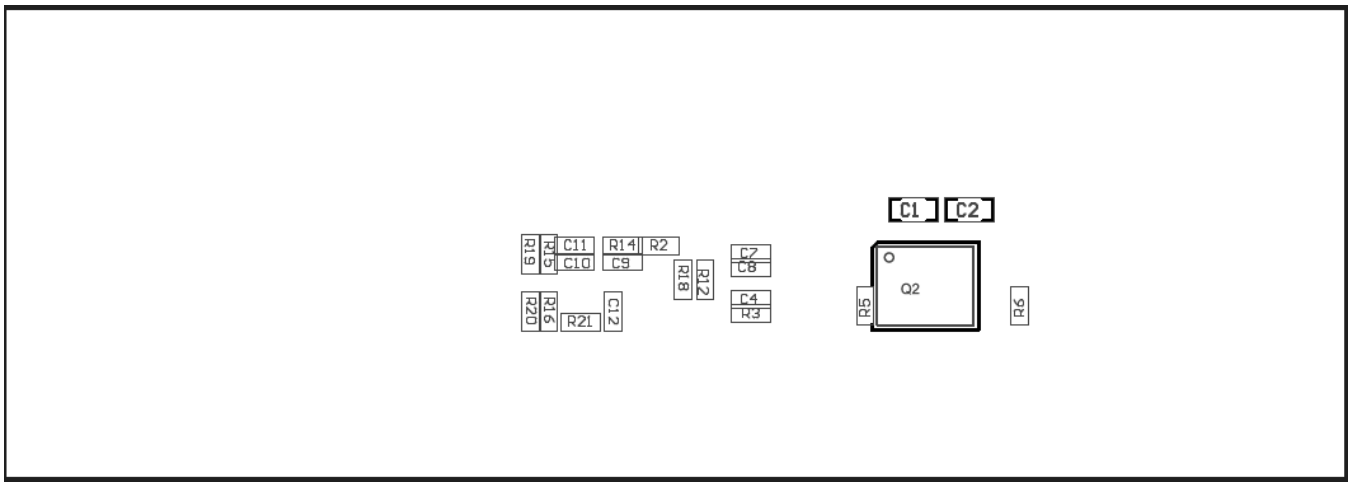


**Figure 17. Bottom Assembly**

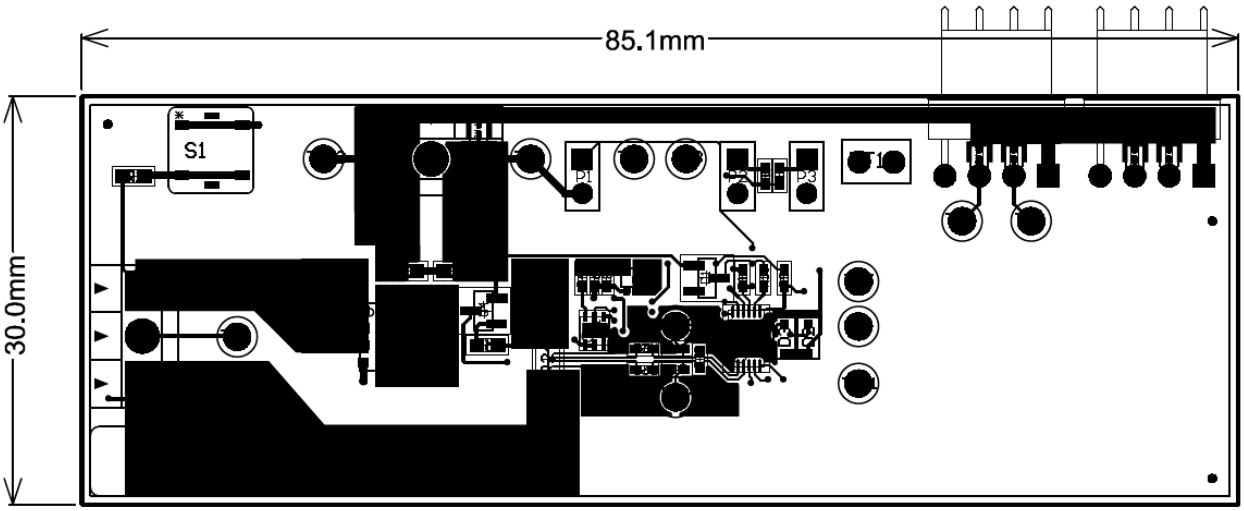


**Figure 18. Top Layer**

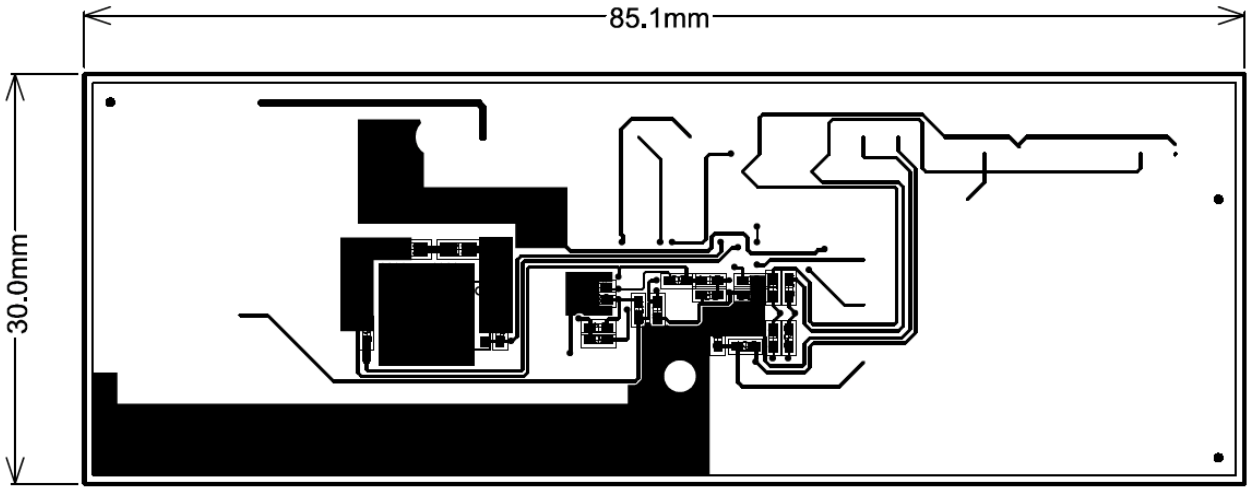


**Figure 19. Bottom Layer**

## 4.2 Bill of Materials and Schematic

**Table 3. Bill of Materials**

| Designator | Quantity | Value | Description | Package Reference | PartNumber | Manufacturer |
|---|---|---|---|---|---|---|
| C1, C2, C3, C5 | 4 | 0.1 µF | Capacitor, Ceramic, 50 V, X7R, 10% | 0603 | CL10B104KB8SFNC | Samsung Electromechanics |
| C4, C6, C7, C8, C10, C13 | 6 | 0.1 µF | Capacitor, Ceramic Chip, 16 V, X7R, 10% | 0402 | CL05B104KO5NNNC | Samsung Electromechanics |
| C9 | 1 | 1 µF | Capacitor, Ceramic Chip, 16 V, X5R, 10% | 0402 | CL05A105KO5NNNC | Samsung Electromechanics |
| C11 | 1 | 2.2 µF | Capacitor, Ceramic Chip, 16 V, X5R, 20% | 0402 | C1005X5R1C225M050 BC | TDK Corporation |
| D1 | 1 | BAS16-7-F | Diode, Ultrafast, 75V, 0.3A, SOT-23 | SOT-23 | BAS16-7-F | Diodes Inc. |
| D2, D3 | 2 | MM3Z5V6C | Diode, Zener, 5.6V, 200 mW | SOD323 | MM3Z5V6C | Fairchild |
| J1, J2 | 2 | ED555/3DS | Terminal Block, 3-pin, 6-A, 3.5 mm | 0.41 x 0.25 inch | ED555/3DS | OST |
| J3 | 1 | | Header (friction lock), 100 mil, 4x1, R/A, TH | 4x1 R/A Header | 22-05-3041 | Molex |
| P1, P2, P3 | 3 | PEC02SAAN | Header, male 2-Pin, 100-mil spacing | 0.100 x 2 | PEC02SAAN | Sullins |
| Q1 | 1 | SI1414DH-T1-GE3 | MOSFET, Nch, 30 V, 4 A, 46 mΩ | SC-70 | SI1414DH-T1-GE3 | Vishay |
| Q2, Q3 | 2 | 25 V | MOSFET, N-CH, 25 V, 52 A, SON 5x6 mm | SON 5x6mm | CSD16412Q5A | Texas Instruments |
| Q4 | 1 | 2N7002K-T1-E3 | MOSFET, Nch, 60 V, 300 mA, 2 Ω | SOT23 | 2N7002K-T1-E3 | Vishay |
| R1 | 1 | 1K | Resistor, Chip, 1/10-W, 5% | 0603 | RC1608J102CS | Samsung Electromechanics |
| R2, R15, R16, R18, R19, R20, R22, R23 | 8 | 100 | Resistor, Chip, 1/16W, 5% | 0402 | RC1005J101CS | Samsung Electromechanics |
| R3, R4, R12 | 3 | 1k | Resistor, Chip, 1/16W, 5% | 0402 | RC1005J102CS | Samsung Electromechanics |
| R5, R6 | 2 | 10M | Resistor, Chip, 1/16W,5% | 0402 | RC1005J106CS | Samsung Electromechanics |
| R7 | 1 | 10K | Resistor, Chip, 1/10-W, 5% | 0603 | RC1608J103CS | Samsung Electromechanics |
| R8 | 1 | 100k | Resistor, Chip, 1/16W, 5% | 0402 | RC1005J104CS | Samsung Electromechanics |
| R9, R10, R13, R17 | 4 | 5.1k | Resistor, Chip, 1/16W, 5% | 0402 | RC1005J512CS | Samsung Electromechanics |
| R11 | 1 | 10 | Resistor, Chip, 1/16W, 5% | 0402 | RC1005J100CS | Samsung Electromechanics |
| R14 | 1 | 4.99 | Resistor, Chip, 1/16W, 5% | 0402 | CRCW04024R99FKED | Vishay Dale |
| R24 | 1 | 0.001 50 ppm | Resistor, Metal Foil, 1 watt, ± 1% | 1206 | CSNL1206FT1L00 | Vishay |
| RT1 | 1 | 10 K | Thermistor, NTC, 3 A | 0.095 X 0.150 inch | 103AT-2 | Semitec |
| S1 | 1 | EVQ-PLHA15 | Switch, Push button, Momentary, 1P1T, 50 mA, 12 V | 0.200 x 0.200 inch | EVQ-PLHA15 | Panasonic |
| SPK1, SPK2, SPK3, SPK4, SPK5 | 5 | | Gap, 0.010" space | 0.020 x 0.020 inch | | |
| TP1, TP3, TP4, TP5, TP7, TP8, TP10, TP12, TP13, TP14 | 10 | Black | Test Point, TH, Miniature, Black | 0.100 x 0.100 inch | 5001 | Keystone |
| TP2, TP6, TP9 | 3 | Red | Test Point, TH, Miniature, Red | 0.100 x 0.100 inch | 5000 | Keystone |

**Table 3. Bill of Materials (continued)**

| Designator | Quantity | Value | Description | Package Reference | PartNumber | Manufacturer |
|---|---|---|---|---|---|---|
| U1 | 1 | BQ294502DRVR | Overvoltage Protection Device for 2 to 3 Cell Li-Ion Batteries, with 4.35 V OVP, -40 to 85 °C, 6-pin SON (DRV), Green (RoHS & no Sb/Br) | DRV0006A | BQ294502DRVR | Texas Instruments |
| U2 | 1 | bq28z610DRZ | 1-Cell to 2-Series Cell Programmable Battery Manager, DRZ0012A | DRZ0012A | bq28z610DRZ | Texas Instruments |
| C12 | 0 | 1 µF | Capacitor, Ceramic Chip, 16 V, X5R, 10% | 0402 | CL05A105KO5NNNC | Samsung Electromechanics |
| C14, C15 | 0 | 0.1 µF | Capacitor, Ceramic Chip, 16 V, X7R, 10% | 0402 | CL05B104KO5NNNC | Samsung Electromechanics |
| J4 | 0 | | Header (friction lock), 100mil, 4x1, R/A, TH | 4x1 R/A Header | 22-05-3041 | Molex |
| R21 | 0 | 330k | Resistor, Chip, 1/16W, 5% | 0402 | RC1005J334CS | Samsung Electromechanics |
| TP11 | 0 | Black | Test Point, TH, Miniature, Black | 0.100 x 0.100 inch | 5001 | Keystone |

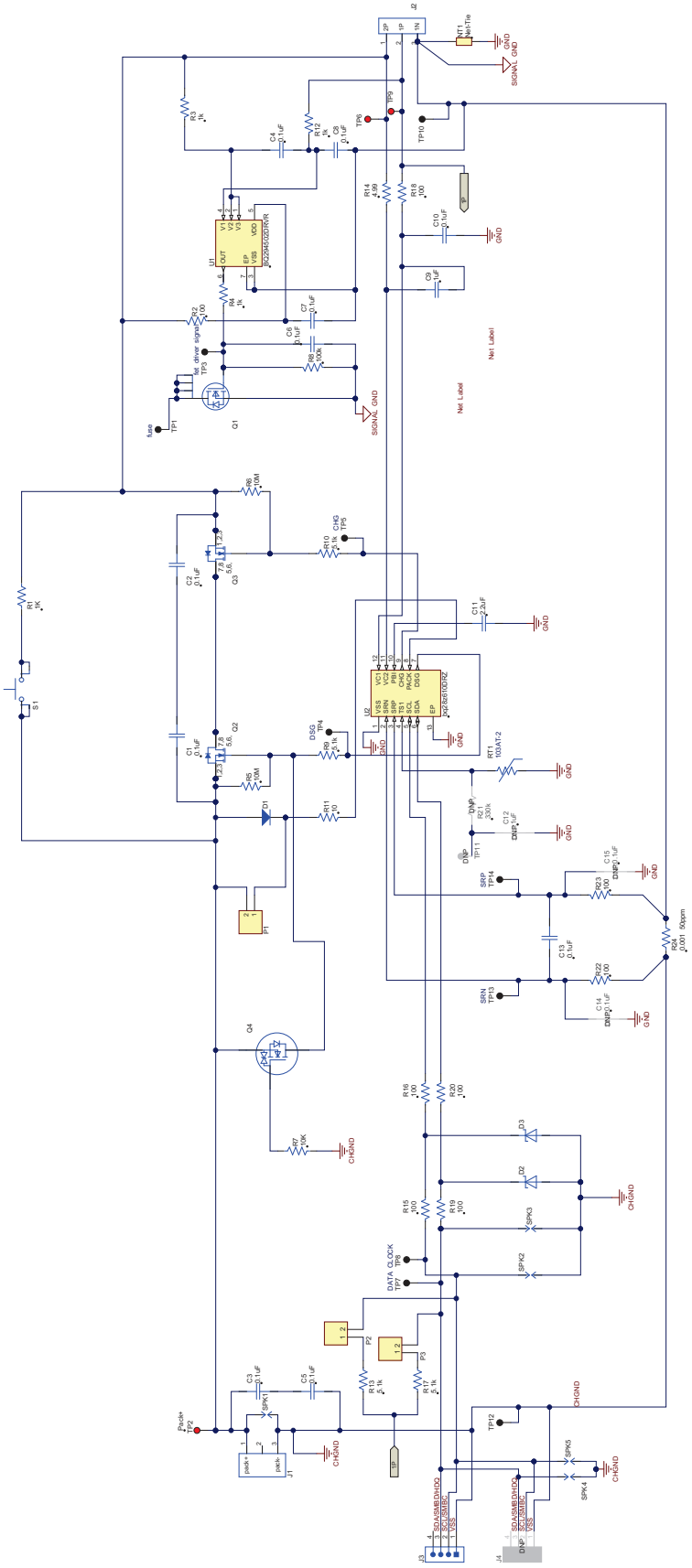

**Figure 20. Schematic**

### 4.3 Testing Fuse-Blowing Circuit

To prevent the loss of board functionality during the fuse-blowing test, the actual chemical fuse is not provided in the circuit. FET Q1 drives TP1 low if a fuse-blow condition occurs; thus, monitoring TP1 can be used to test this condition.

## Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Date | Revision | Notes |
|---|---|---|
| November 2015 | * | Initial Release |

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      3.1.1 *Notice applicable to EVMs not FCC-Approved:*

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      3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

      **CAUTION**

      This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

      Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

      **FCC Interference Statement for Class A EVM devices**

      *NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.*

**FCC Interference Statement for Class B EVM devices**

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- *Reorient or relocate the receiving antenna.*
- *Increase the separation between the equipment and receiver.*
- *Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.*
- *Consult the dealer or an experienced radio/TV technician for help.*

3.2 *Canada*

3.2.1 *For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210*

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**Concernant les EVMs avec appareils radio:**

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

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Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

**Concernant les EVMs avec antennes détachables**

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur

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2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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